

ABSTRACT

A surface mount power supply device and a method for mounting a lead frame to a circuit board, which has a first and second side, and assembling such a device. The lead frame has leads with a lead solder area for contact with solder material on the circuit board. According to the method, the lead frame and a first set of electrical components are reflow soldered on the first side of the circuit board. Then the circuit board is inverted and a second set of electrical components are reflow soldered on the second surface of the circuit board. The lead solder area and in particular the ratio of the weight of the frame to the lead solder area is chosen so that the lead frame remains connected to the first side of circuit board during the second reflow soldering.

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